TEXAS INSTRUMENTS
Data sheet acquired from Harris Semiconductor
SCHS042C – Revised July 2003

CD4045B Types

CMOS 21-Stage Counter

High-Voltage Types (20-Volt Rating)

■ CD4045B is a timing circuit consisting of 21 counter stages, two output-shaping flip-flops, two inverter output drivers, and input inverters for use in a crystal oscillator. The CD4045B configuration provides 21 flip-flop counting stages, and two flip-flops for shaping the output waveform for a 3.125% duty cycle. Push-pull operation is provided by the inverter output drivers.

The first inverter is intended for use as a crystal oscillator/amplifier. However, it may be used as a normal logic inverter if desired. A crystal oscillator circuit can be made less sensitive to voltage-supply variations by the use of source resistors. In this device, the sources of the p and n transistors have been brought out to package terminals. If external resistors are not required, the sources must be shorted to their respective substrates (S_p to V_{DD}, S_n to V_{SS}). See Fig. 1. The first inverter in conjunction with an outboard inverter, such as 1/6 CD4069, and R_X, C_X, and R_S can also be used to construct an RC oscillator. The following data is supplied as a guide in the selection of values for R_X, R_S, and C_X used in Fig. 11:

1. R_X max = 10 MΩ with R_S = 10 MΩ and C_X = 50 pF
2. C_X max = 25 μF with R_S = 560 kΩ and R_X = 50 kΩ

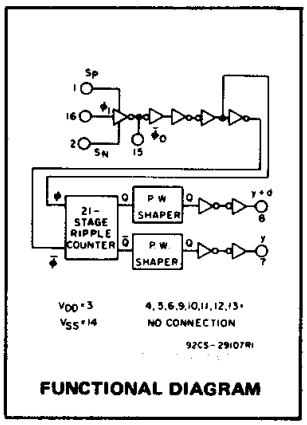
The CD4045B types are supplied in 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline package (NSR suffix), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

Applications:

- **Digital equipment in which ultra-low dissipation and/or operation using a battery source is required.**
- **Accurate timing from a crystal oscillator for timing applications such as wall clocks, table clocks, automobile clocks, and digital timing references in any circuit requiring accurately timed outputs at various intervals in the counting sequence.**
- **Driving miniature synchronous motors, stepping motors, or external bipolar transistors in push-pull fashion.**

Features:

- **Very low operating dissipation . . . . . <1 mW (typ.) @ V_{DD} = 5 V, fϕ = 1 MHz**
- **Output drivers with sink or source capability . . . . . 7 mA (typ.) @ V_{DD} = 5 V**
- **Medium speed (typ.) . . . fϕ = 25 MHz @ V_{DD} = 10 V**
- **100% tested for quiescent current at 20 V**
- **5-V, 10-V, and 15-V parametric ratings**
- **Meets all requirements of JEDEC Tentative Standard No. 13B, Standard Specifications for Descripiton of 'B' Series CMOS Devices"**



FUNCTIONAL DIAGRAM

MAXIMUM RATINGS, *Absolute-Maximum Values:*

DC SUPPLY-VOLTAGE RANGE, (V_{DD})
(Voltages referenced to V_{SS} Terminal) ..... -0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS ..... -0.5V to V_{DD} +0.5V
DC INPUT CURRENT, ANY ONE INPUT ..... ±10mA
POWER DISSIPATION PER PACKAGE (P_D):
For T_A = -55°C to +100°C 500mW
For T_A = +100°C to +125°C ..... Derate Linearity at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR
FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW
OPERATING-TEMPERATURE RANGE (T_A) ..... -55°C to +125°C
STORAGE TEMPERATURE RANGE (T_{stg}) ..... -65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):
At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max ..... +265°C

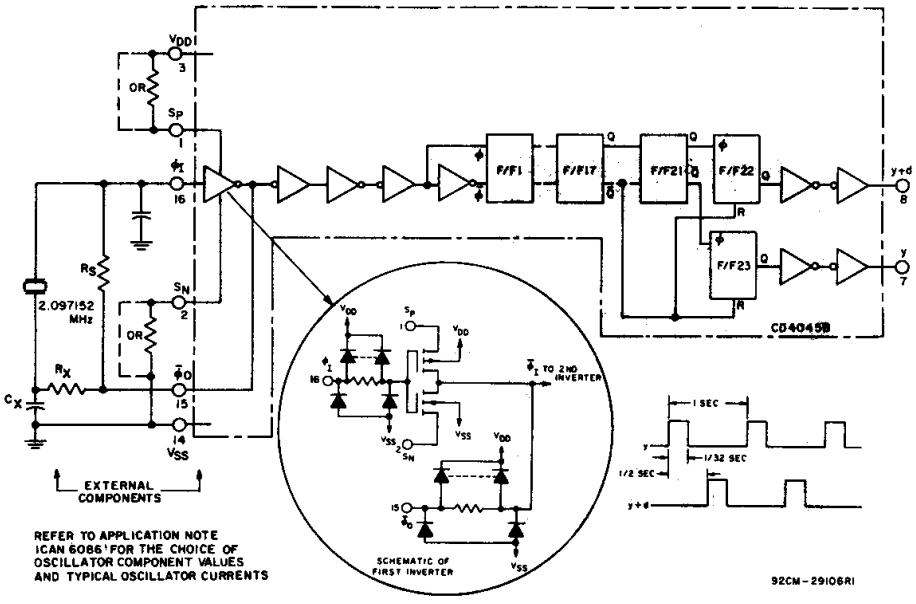


Fig. 1 – CD4045B and outboard components in a typical 21-stage counter application.

STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V_O (V)	V_{IN} (V)	V_{DD} (V)	−55	−40	+85	+125	+25 Min.	+25 Typ.	+25 Max.	
Quiescent Device Current, I_{DD} Max.	–	0,5	5	5	5	150	150	–	0.04	5	μA
	–	0,10	10	10	10	300	300	–	0.04	10	
	–	0,15	15	20	20	600	600	–	0.04	20	
	–	0,20	20	100	100	3000	3000	–	0.08	100	
Output Low (Sink) Current I_{OL} Min.	0.4	0,5	5	4.5	4.3	2.9	2.5	3.6	7	–	mA
	0.5	0,10	10	11.2	10.5	7.7	6.3	9.1	18	–	
	1.5	0,15	15	29.4	28	19.6	16.8	23.8	47	–	
Output High (Source) Current, I_{OH} Min.	4.6	0,5	5	−4.5	−4.3	−2.9	−2.5	−3.6	−7	–	
	9.5	0,10	10	−11.2	−10.5	−7.7	−6.3	−9.1	−18	–	
	13.5	0,15	15	−29.4	−28	−19.6	−16.8	−23.8	−47	–	
Pin 15 Output Low and High Current, I_{OL}, I_{OH}	0.4,4.6	0,5	5	–				±0.1	±0.18	–	mA
	0.5,9.5	0,10	10	–				±0.2	±0.3	–	
	1.5,13.5	0,15	15	–				±0.5	±1	–	
Output Voltage: Low-Level, V_{OL} Max.	–	0,5	5	0.05				–	–	0.05	V
	–	0,10	10	0.05				–	–	0.05	
	–	0,15	15	0.05				–	–	0.05	
Output Voltage: High-Level, V_{OH} Min.	–	0,5	5	4.95				4.95	5	–	
	–	0,10	10	9.95				9.95	10	–	
	–	0,15	15	14.95				14.95	15	–	
Input Low Voltage V_{IL} Max.	0.5,4.5	–	5	1.5				–	–	1.5	V
	1,9	–	10	3				–	–	3	
	1.5,13.5	–	15	4				–	–	4	
Input High Voltage, V_{IH} Min.	0.5,4.5	–	5	3.5				3.5	–	–	
	1,9	–	10	7				7	–	–	
	1.5,13.5	–	15	11				11	–	–	
Input Current I_{IN} Max.	–	0,18	18	±0.1	±0.1	±1	±1	–	$\pm 10^{-5}$	±0.1	μA

RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges

CHARACTERISTIC	V_{DD} (V)	LIMITS Min.	LIMITS Max.	UNITS
Supply-Voltage Range (For T_A = Full Package-Temperature Range)	–	3	18	V
Minimum Input-Pulse Width, t_W	5	–	100	ns
	10	–	50	
	15	–	40	
Maximum Input–Pulse Frequency, fϕ (External Pulse Source)	5	5	–	MHz
	10	12	–	
	15	15	–	

DYNAMIC ELECTRICAL CHARACTERISTICS at T_A = 25°C; Input t_r, t_f = 20 ns, C_L = 50 pF, R_L = 200 kΩ

CHARACTERISTIC	TEST CONDITIONS	V_{DD} V	LIMITS Min.	Typ.	Max.	UNITS
Propagation Delay Time: ϕ_I to y or y+d out t_{PHL}, t_{PLH}		5	–	2.2	5.5	μs
		10	–	0.9	2.7	
		15	–	0.65	2	
Transition Time: t_{THL}, t_{TLH}		5	–	25	50	ns
		10	–	13	25	
		15	–	10	20	
Minimum Input-Pulse Width t_W		5	–	50	100	
		10	–	25	50	
		15	–	20	40	
Input-Pulse Rise or Fall Time: $t_r\phi$, $t_f\phi$		5	–	–	500	μs
		10	–	–	500	
		15	–	–	500	
Maximum Input-Pulse Frequency: (External Pulse Source) f_ϕ		5	5	10	–	MHz
		10	12	25	–	
		15	15	30	–	
Input Capacitance, C_{IN}	Any Input		–	5	7.5	pF
Variation of Output Frequency (Unit-to-Unit)	f = 5 MHz	5	–	0.05	–	%
		10	–	0.03	–	
		15	–	0.1	–	
RC Oscillator Operation						
Maximum Oscillator Frequency (See Fig. 11) f_{osc}	R_X = 50 kΩ, R_S = 560 kΩ, C_X = 50 pF	5	45	60	75	kHz
		10	45	60	75	
		15	45	60	75	

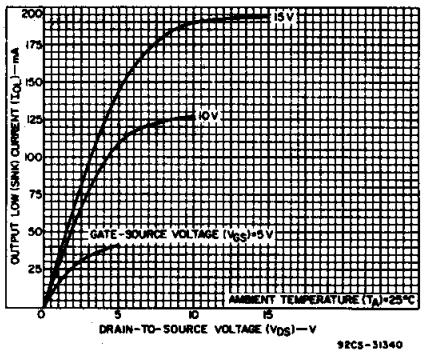


Fig. 2 – Typical output low (sink) current characteristics.

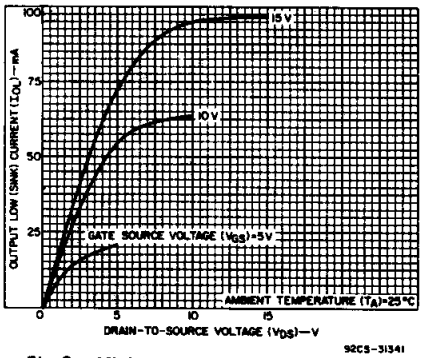


Fig. 3 – Minimum output low (sink) current characteristics.

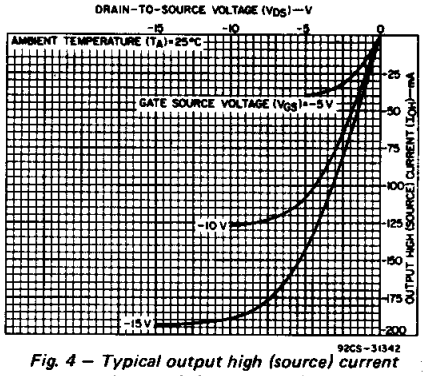


Fig. 4 – Typical output high (source) current characteristics.

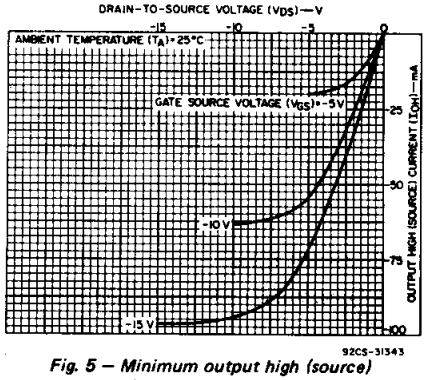


Fig. 5 – Minimum output high (source) characteristics.

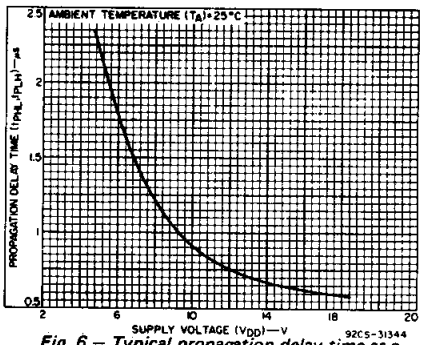


Fig. 6 – Typical propagation delay time as a function of supply voltage (ϕ_I to y or y + d out vs. V_{DD}).

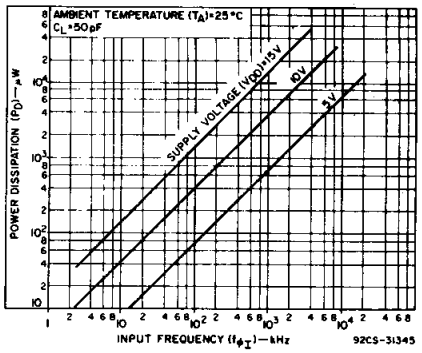


Fig. 7 – Typical power dissipation as a function of input frequency (21 counting stages).

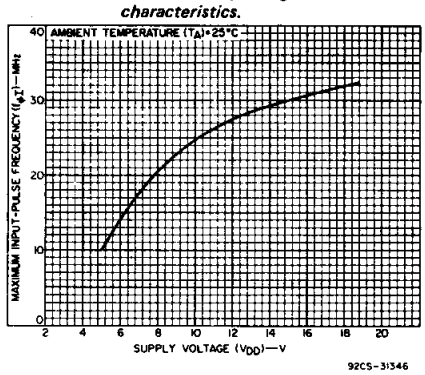


Fig. 8 – Typical maximum input-pulse frequency as a function of supply voltage.

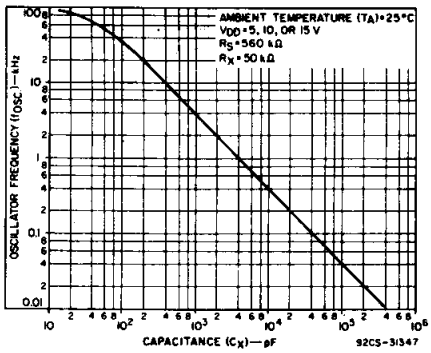


Fig. 9 – Typical RC oscillator frequency as a function of capacitance (C_X), See Fig. 11.

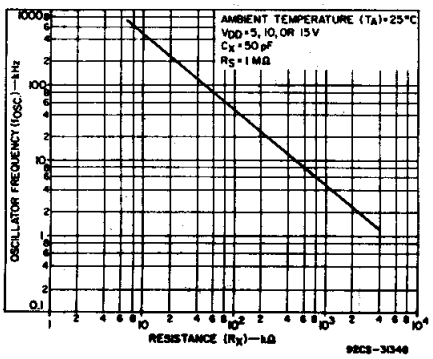


Fig. 10 – Typical RC oscillator frequency as a function of resistance (R_X), See Fig. 11.

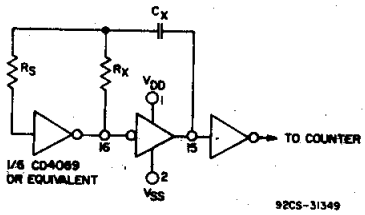


Fig. 11 – Typical RC circuit.

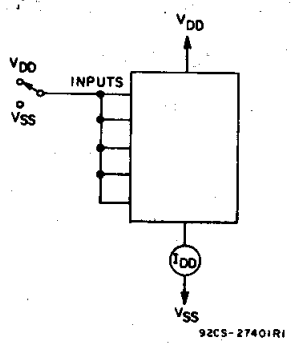


Fig. 12 – Quiescent-device-current test circuit.

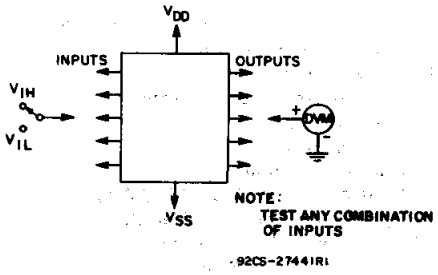


Fig. 13 – Noise-immunity test circuit.

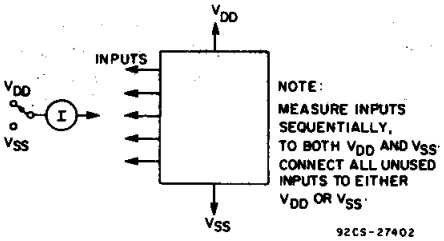


Fig. 14 – Input-leakage-current test circuit.

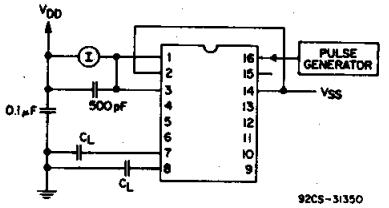
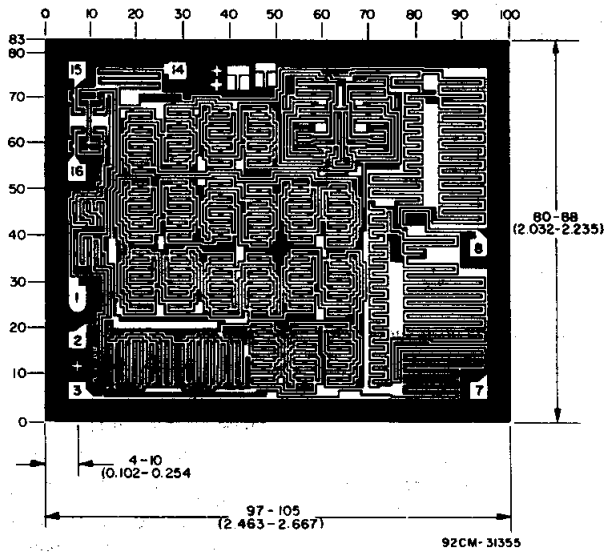


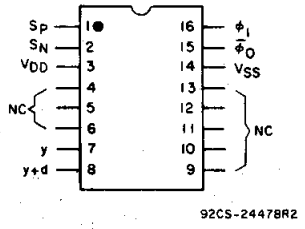
Fig. 15 – Dynamic power dissipation test circuit.



Chip dimensions and pad layout for CD4045B

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

TERMINAL DIAGRAM
Top View



NC = NO CONNECTION

NOTE Observe power-supply terminal connections, V_{DD} is terminal No. 3 and V_{SS} is terminal No. 14 (not 16 and 8 respectively, as in other CD4000B Series 16-lead devices).

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD4045BE	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD4045BE	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

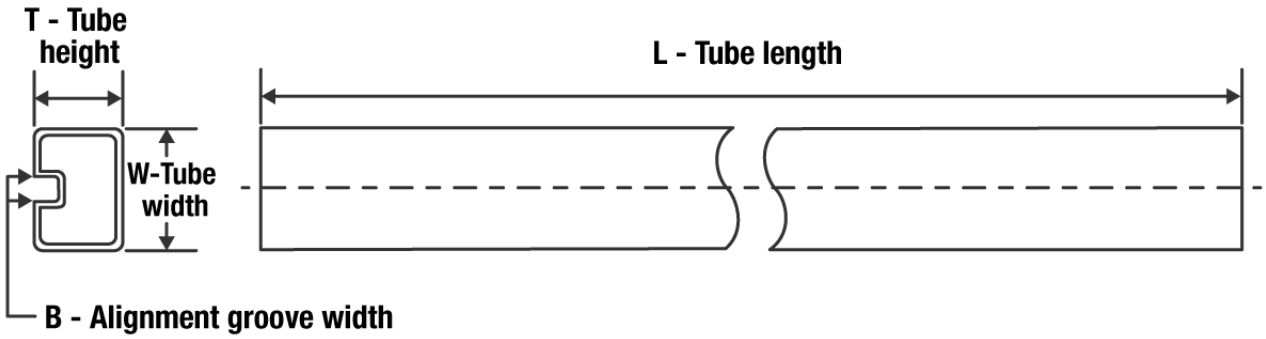
(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

TUBE



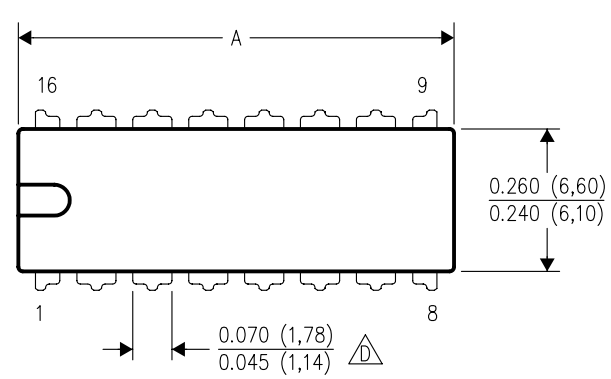
*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD4045BE	N	PDIP	16	25	506	13.97	11230	4.32
CD4045BE	N	PDIP	16	25	506	13.97	11230	4.32

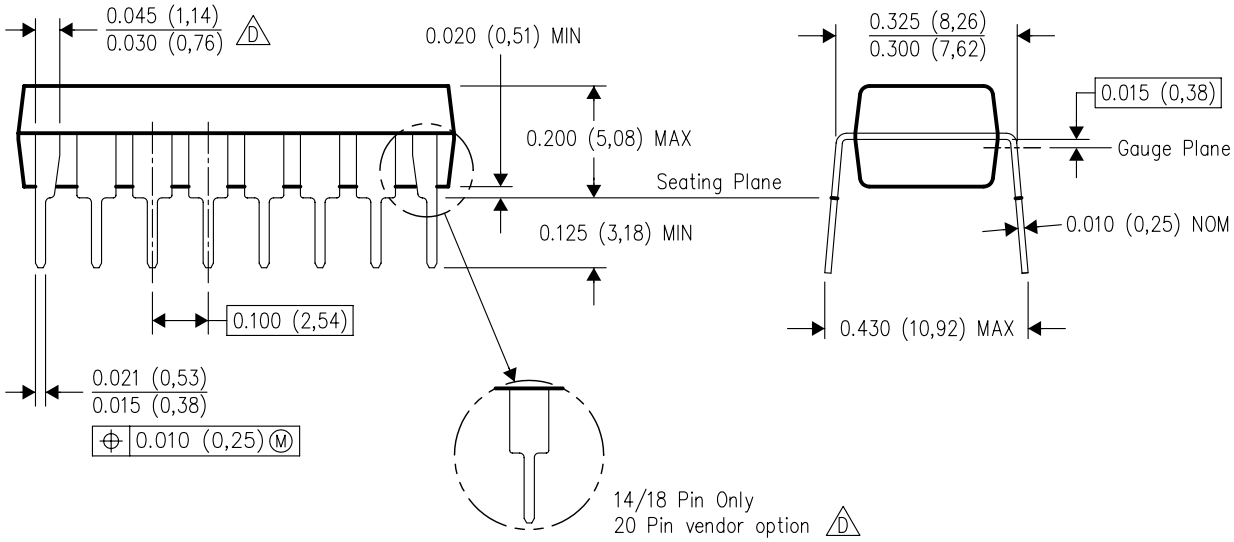
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



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NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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